CORFIL® 625-1

Adhesive

Cytec Industries Inc.

Message:

CORFIL® 625-1 potting compound is a one-part, low density material formulated for use in insert and edge filling of honeycomb core. It may also be used as a syntactic core splice adhesive. It is formulated to have low viscosity making it especially suitable for use with automated equipment. CORFIL 625-1 can be cured at either 250°F (121°C) or 350°F (177°C) with minimal to no exotherm in large applications.
FEATURES & BENEFITS
One-part pumpable material
250°F (121°C)/ 350°F (177°C) cure
Minimal exotherm
-67 to 350°F (-55 to 177°C) service range

General Information	
Features	Low Viscosity Thixotropic
Uses	Adhesives Filling Applications Structural Parts
Appearance	White
Forms	Paste
Processing Method	Potting

Mechanical	Nominal Value	Unit
Compressive Strength (24°C)	20.7 to 21.4	MPa
Shear Strength [1] (24°C)	6.89 to 8.27	MPa

NOTE	
1.	Filled Tube

WECHAT